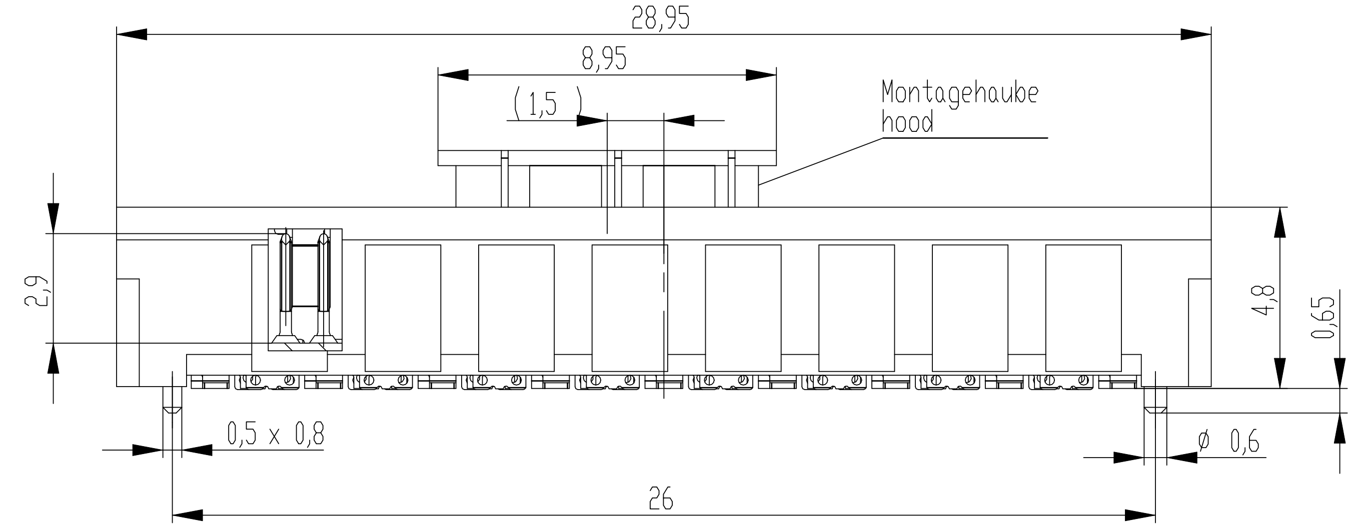
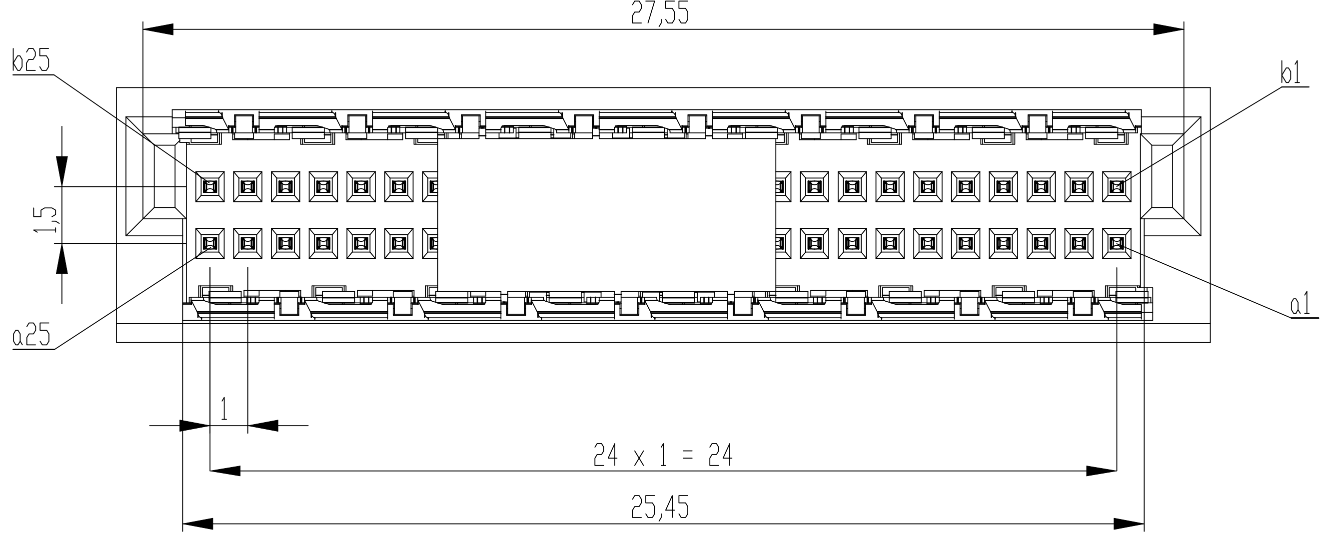
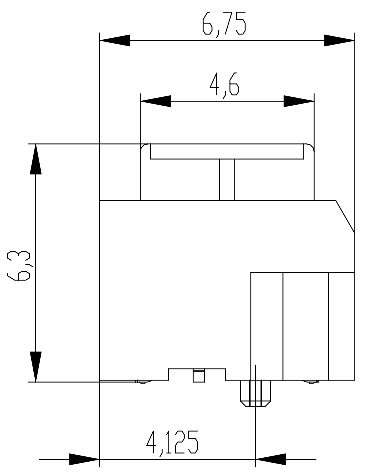
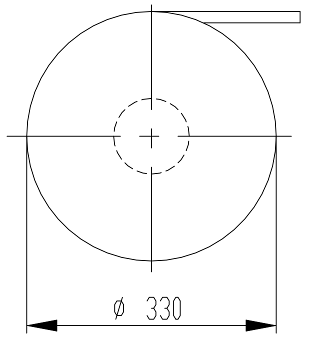
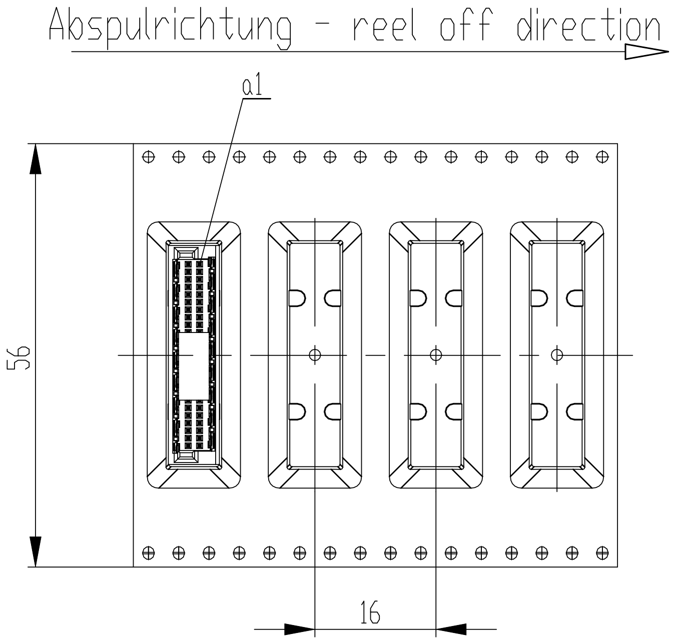




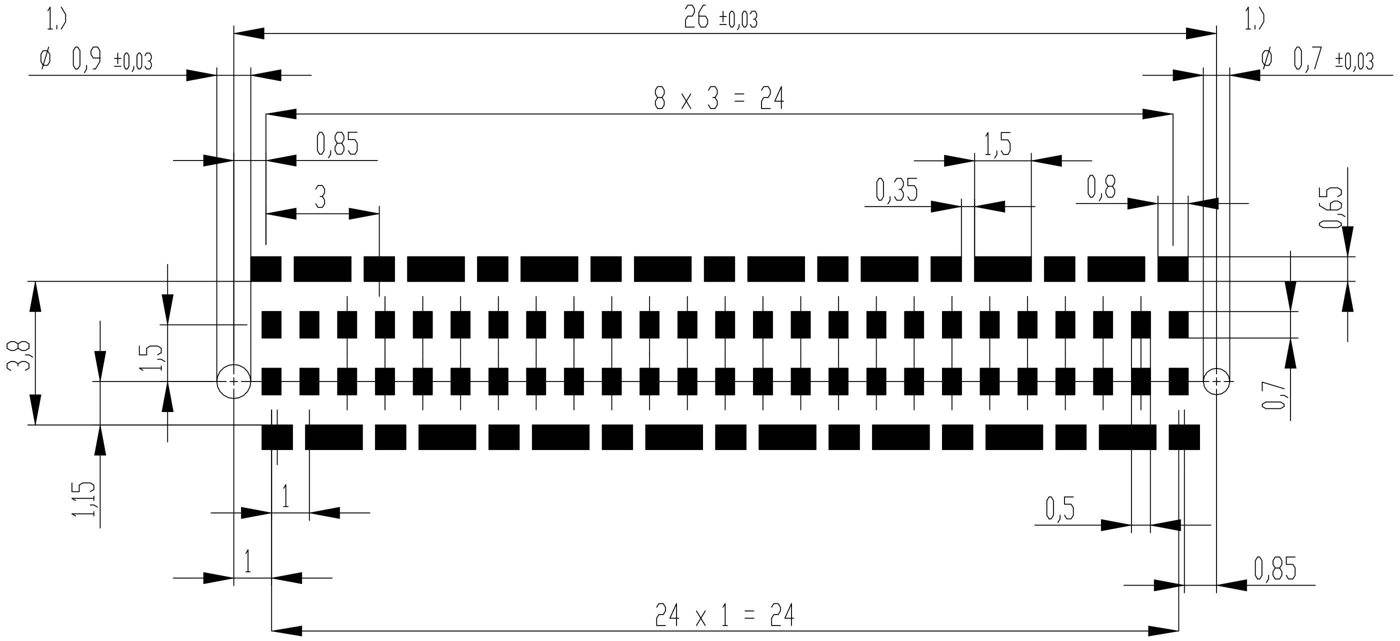


Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 400 Stück
packaging unit: 400 pcs





Leiterplatten-Layout Vorschlag / PCB-layout proposal



Für weitere Layout Details
bitte Applikations Schrift
MicroSpeed beachten.
For further layout details
please consider
MicroSpeed application note.

1.) Durchmesser des Bohrers / Drill tool

Anforderungsstufe 1
performance level 1

Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinnt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

Dimension no.

Tolerances
Dim. for Information
ISO 8015

All Dimensions
in mm

Scale 5:1
Material

Customer drawing:
THIS DRAWING IS A CONTROLLED
DOCUMENT.

Subject to modification without
prior notice.
Drawing will not be updated.

ERNI-Messerl. 1mm SMD 50pol. BM EMV
Male 1mm SMD 50 cont. BM EMV

TE Connectivity

C-374723-E
I
A3

e 28.01.2014
Index Date

Class MSPEED